

Absolute Maximum Ratings

Parameter	IRFM150, JANTXV, JANTX-, 2N7224	Units
I_D @ $V_{GS} = 10V$, $T_C = 25^\circ C$ Continuous Drain Current	34	A
I_D @ $V_{GS} = 10V$, $T_C = 100^\circ C$ Continuous Drain Current	21	
I_{DM} Pulsed Drain Current ①	136	
P_D @ $T_C = 25^\circ C$ Max. Power Dissipation	150	W
Linear Derating Factor	1.2	W/K ⑤
V_{GS} Gate-to-Source Voltage	± 20	V
E_{AS} Single Pulse Avalanche Energy ②	150 (See Fig. 12)	mJ
I_{AR} Avalanche Current ①	34 (See E_{AR})	A
E_{AR} Repetitive Avalanche Energy ①	15 (See Fig. 13)	mJ
dv/dt Peak Diode Recovery dv/dt ③	5.5 (See Fig. 13)	V/ns
T_J Operating Junction Temperature	-55 to 150	$^\circ C$
T_{STG} Storage Temperature Range		
Lead Temperature	300 (0.063 in. (1.6 mm) from case for 10s)	
Weight	9.3 (typical)	g

Electrical Characteristics @ $T_J = 25^\circ C$ (Unless Otherwise Specified)

Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS} Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0V$, $I_D = 1.0$ mA
$\Delta BV_{DSS}/\Delta T_J$ Temperature Coefficient of Breakdown Voltage	—	0.13	—	V/ $^\circ C$	Reference to $25^\circ C$, $I_D = 1.0$ mA
$R_{DS(on)}$ Static Drain-to-Source On-State Resistance	—	—	0.07	Ω	$V_{GS} = 10V$, $I_D = 21A$ ④
	—	—	0.081		
$V_{GS(th)}$ Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250$ μA
g_{fs} Forward Transconductance	9.0	—	—	S (⑥)	$V_{DS} \geq 15V$, $I_{DS} = 21A$ ④
I_{DSS} Zero Gate Voltage Drain Current	—	—	25	μA	$V_{DS} = 0.8 \times$ Max. Rating, $V_{GS} = 0V$
	—	—	250		$V_{DS} = 0.8 \times$ Max. Rating $V_{GS} = 0V$, $T_J = 125^\circ C$
I_{GSS} Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20V$
I_{GSS} Gate-to-Source Leakage Reverse	—	—	-100		$V_{GS} = -20V$
Q_g Total Gate Charge	50	—	125	nC	$V_{GS} = 10V$, $I_D = 34A$
Q_{gs} Gate-to-Source Charge	8	—	22		$V_{DS} = 0.5 \times$ Max. Rating
Q_{gd} Gate-to-Drain ("Miller") Charge	15	—	65		See Fig. 6 and 14
$t_{d(on)}$ Turn-On Delay Time	—	—	35	ns	$V_{DD} = 50V$, $I_D = 34A$, $R_G = 2.35\Omega$
t_r Rise Time	—	—	190		See Fig. 11
$t_{d(off)}$ Turn-Off Delay Time	—	—	170		
t_f Fall Time	—	—	130		
L_D Internal Drain Inductance	—	8.7	—	nH	Measured from the drain lead, 6 mm (0.25 in.) from package to center of die.
L_S Internal Source Inductance	—	8.7	—		Measured from the source lead, 6 mm (0.25 in.) from package to source bonding pad.
C_{iss} Input Capacitance	—	3700	—	pF	$V_{GS} = 0V$, $V_{DS} = 25V$
C_{oss} Output Capacitance	—	1100	—		$f = 1.0$ MHz
C_{rss} Reverse Transfer Capacitance	—	200	—		See Fig. 5
C_{DC} Drain-to-Case Capacitance	—	12	—		



Source-Drain Diode Ratings and Characteristics

Parameter		Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	34	A	Modified MOSFET symbol showing the integral Reverse p-n junction rectifier. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	136		
V_{SD}	Diode Forward Voltage	—	—	1.8	V	$T_J = 25^\circ\text{C}$, $I_S = 34\text{A}$, $V_{GS} = 0\text{V}$ ④
t_{rr}	Reverse Recovery Time	—	—	500	nS	$T_J = 25^\circ\text{C}$, $I_F = 34\text{A}$, $di/dt \leq 100\text{ A}/\mu\text{s}$ ④
Q_{RR}	Reverse Recovery Charge	—	—	2.9	μC	$V_{DD} \leq 50\text{V}$
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$.				

Thermal Resistance

Parameter		Min.	Typ.	Max.	Units	Test Conditions
R_{thJC}	Junction-to-Case	—	—	0.83	K/W ⑤	
R_{thCS}	Case-to-Sink	—	0.21	—		Mounting surface flat, smooth, and greased
R_{thJA}	Junction-to-Ambient	—	—	48		Typical socket mount

① Repetitive Rating: Pulse width limited by maximum junction temperature (see figure 9)
Refer to current HEXFET reliability report

② @ $V_{DD} = 25\text{V}$, Starting $T_J = 25^\circ\text{C}$,
 $L \geq 200\text{ }\mu\text{H}$, $R_G = 25\Omega$,
Peak $I_L = 34\text{A}$

③ $I_{SD} \leq 34\text{A}$, $di/dt \leq 70\text{ A}/\mu\text{s}$,
 $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^\circ\text{C}$
Suggested $R_G = 2.35\text{ }\Omega$

④ Pulse width $\leq 300\text{ }\mu\text{s}$; Duty Cycle $\leq 2\%$

⑤ $K/W = ^\circ\text{C}/W$
 $W/K = W/^\circ\text{C}$

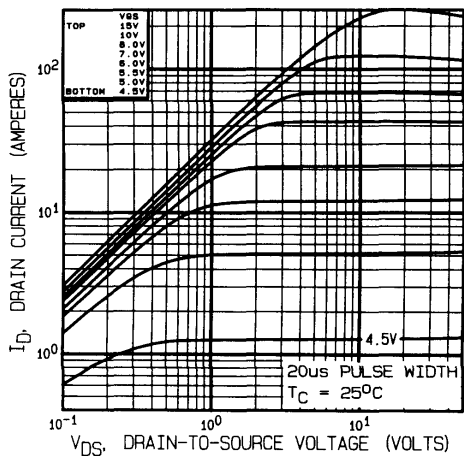


Fig. 1 — Typical Output Characteristics, $T_C = 25^\circ\text{C}$

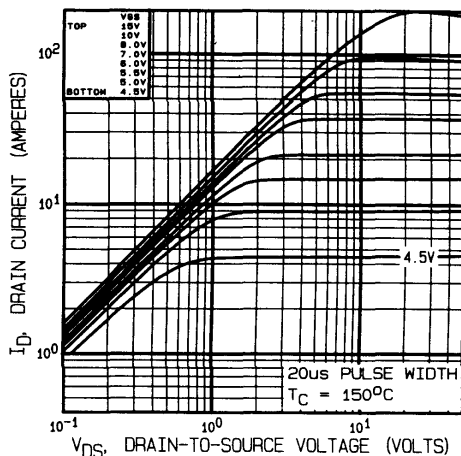


Fig. 2 — Typical Output Characteristics, $T_C = 150^\circ\text{C}$

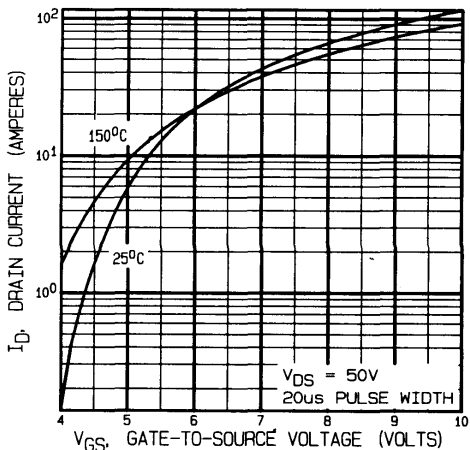


Fig. 3 — Typical Transfer Characteristics

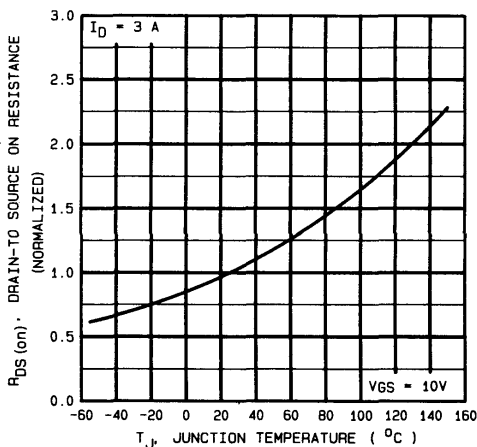
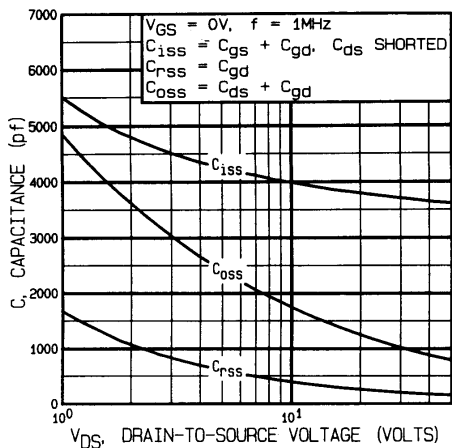
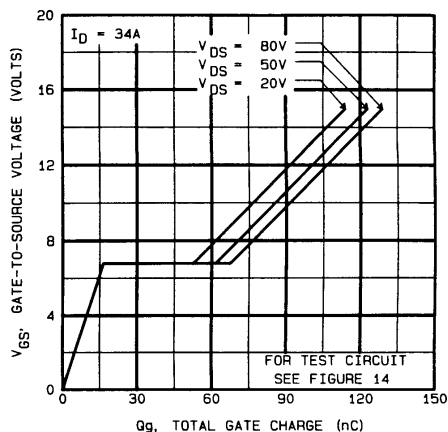
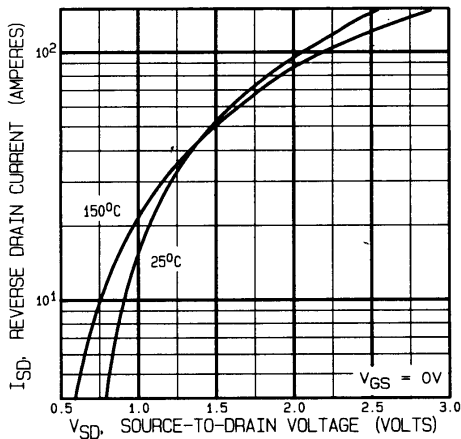
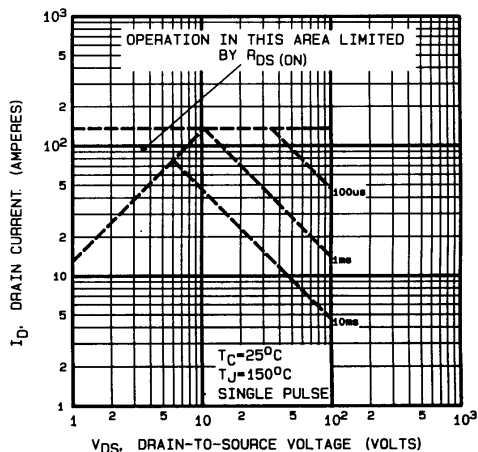


Fig. 4 — Normalized On-Resistance Vs. Temperature


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

Fig. 7 — Typical Source-Drain Diode Forward Voltage

Fig. 8 — Maximum Safe Operating Area

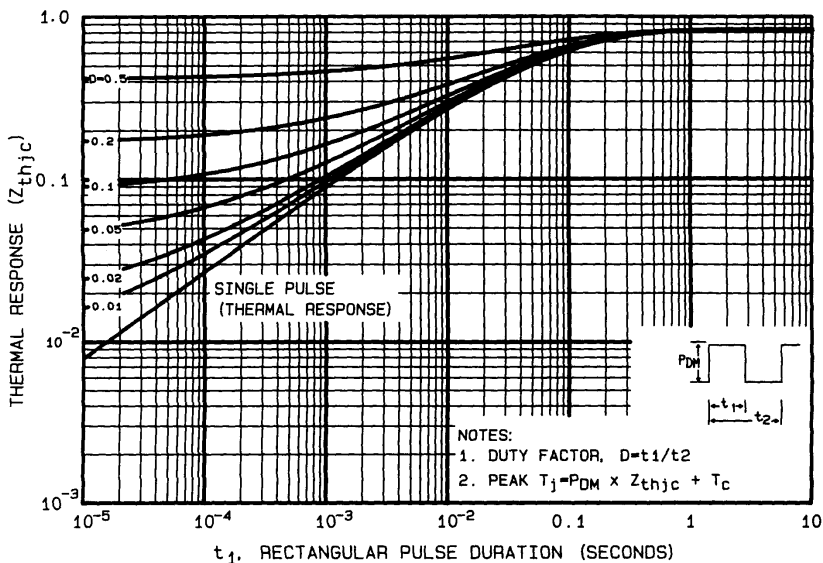


Fig. 9 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

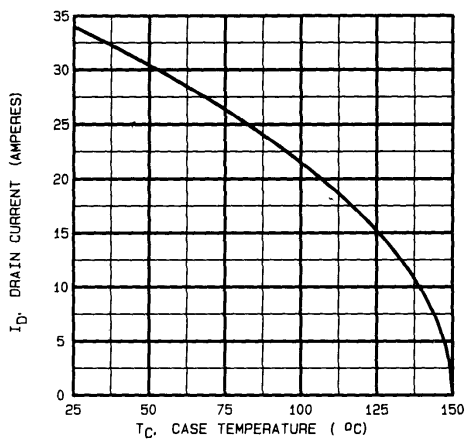


Fig. 10 — Maximum Drain Current Vs. Case Temperature

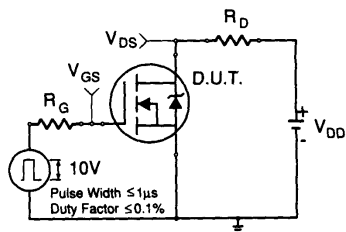


Fig. 11a — Switching Time Test Circuit

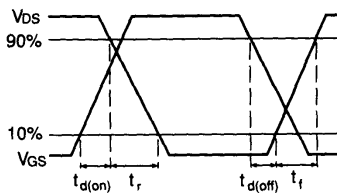
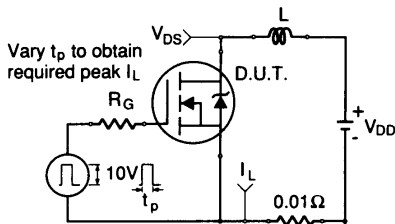
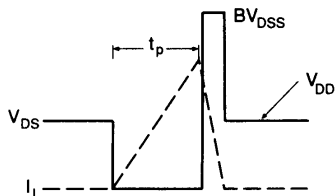
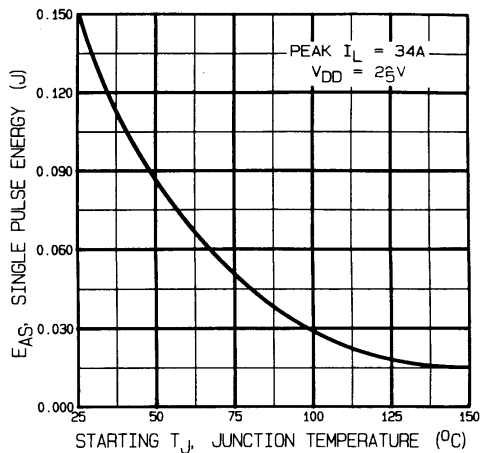
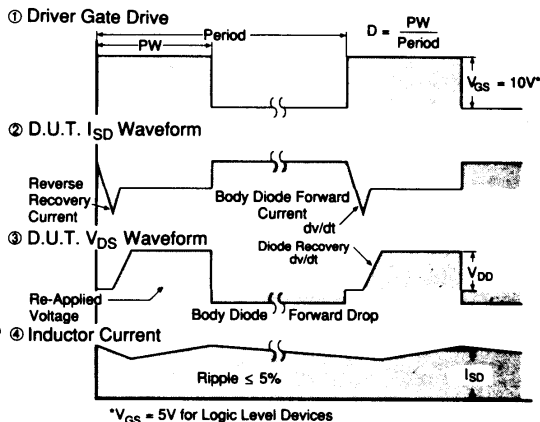
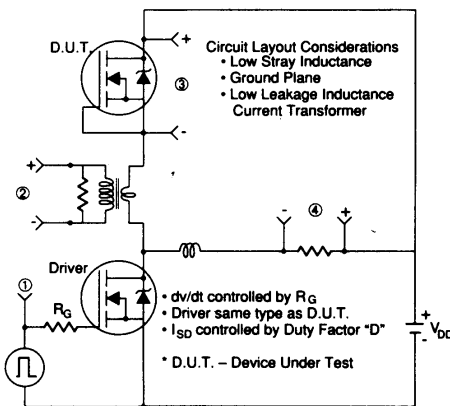


Fig. 11b — Switching Time Waveforms


Fig. 12a — Unclamped Inductive Test Circuit

Fig. 12b — Unclamped Inductive Waveforms

Fig. 12c — Maximum Avalanche Energy Vs. Starting Junction Temperature

Fig. 13 — Peak Diode Recovery dv/dt Test Circuit

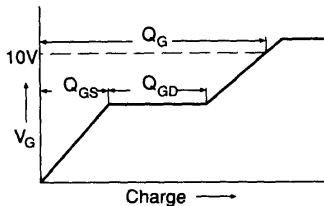


Fig. 14a — Basic Gate Charge Waveform

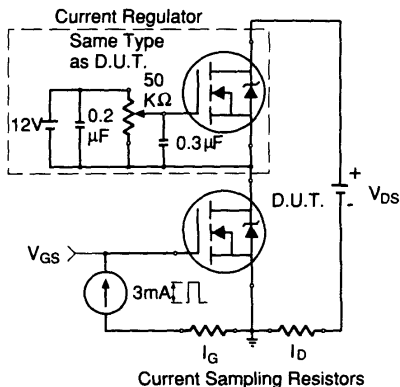


Fig. 14b — Gate Charge Test Circuit

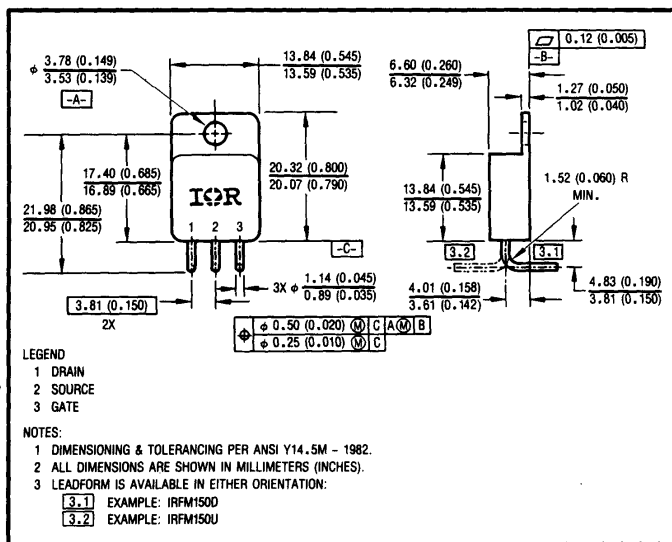


Fig. 15 — Optional Leadforms for Outline TO-254

BERYLLIA WARNING PER MIL-S-19500

Packages containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.